



Product Change Notification: DSNO-14MMPT787

Date:

25-Jul-2025

Product Category:

8-Bit Microcontrollers, Capacitive Touch Sensors

Notification Subject:

CCB 7550 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material for selected ATTINY1624, ATTINY3224, ATTINY424, ATTINY824, AVR16EB14, AVR32EB14, MTCH1030, PIC16F13123, PIC16F13124, PIC16F13125, PIC16F15223, PIC16F15224, PIC16F15225, PIC16F17124, PIC16F17125, PIC16F17126, PIC16F18023, PIC16F18024, PIC16F18025, PIC16F18026, PIC16F18124, PIC16F18125 and PIC16F18126 device families available in 14L TSSOP (4.4mm) package at MMT assembly site.

Affected CPNs:

[DSNO-14MMPT787_Affected_CPN_07252025.pdf](#)

[DSNO-14MMPT787_Affected_CPN_07252025.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material for selected ATTINY1624, ATTINY3224, ATTINY424, ATTINY824, AVR16EB14, AVR32EB14, MTCH1030, PIC16F13123, PIC16F13124, PIC16F13125, PIC16F15223, PIC16F15224, PIC16F15225, PIC16F17124, PIC16F17125, PIC16F17126, PIC16F18023, PIC16F18024, PIC16F18025, PIC16F18026, PIC16F18124, PIC16F18125 and PIC16F18126 device families available in 14L TSSOP (4.4mm) package at MMT assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change
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Assembly Site	Microchip Technology Thailand (Branch) (MMT)			Microchip Technology Thailand (Branch) (MMT)
Wire Material	Au			Au CuPdAu
Die Attach Material	2200D			2200D
Molding Compound Material	G600V			G600V
Lead-Frame Material	C7025			C7025

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying CuPdAu as an additional bond wire material.

Change Implementation Status: In Progress

Estimated First Ship Date: 23 August 2025 (date code: 2534)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	May 2025					>	July 2025				August 2025					
Work Week	18	19	20	21	22		27	28	29	30	31	32	33	34	35	36
Initial PCN Issue Date		X														
Qual Report Availability											X					
Final PCN Issue Date											X					
Estimated Implementation Date														X		

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_{PCN}_Qual_Report.

Revision History: May 06, 2025: Issued initial notification.

July 25, 2025: Issued final notification. Updated the affected parts list to include the AVR32EB14 device family. Attached the Qualification Report. Provided the estimated first ship date to be on August 23, 2025.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[**PCN_DSNO-14MMPT787_Qual Report.pdf**](#)

Please contact your local [**Microchip sales office**](#) with questions or concerns regarding this notification.

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